

## **Texas Instruments**

### PMP4335 Test Procedure

**China Power Reference Design** 

REV A

8/13/2011

### 1 **GENERAL**

#### 1.1 PURPOSE

To provide detailed data for evaluating and verifying the PMP4335, which used TI new Primary Side CC/CV Controller UCC28700 for 5V1A mobile charger with 22mmx21mmx20mm. The below photo shows this demo board.





### 1.2 REFERENCE DOCUMENTATION

Schematic PMP4335\_SCH.PDF Assembly PMP4335\_PCB.PDF BOM

**1.3 TEST EQUIPMENTS**Power-meter: YOKOGAWA WT210 Multi-meter(current): Fluke 8845A Multi-meter(voltage): Fluke 187 AC Source: Chroma 61530 E-load: Chroma 63110A module E-load: Chroma 63105 module Testing demobaord: PMP4335B

#### 1.4 Specifications

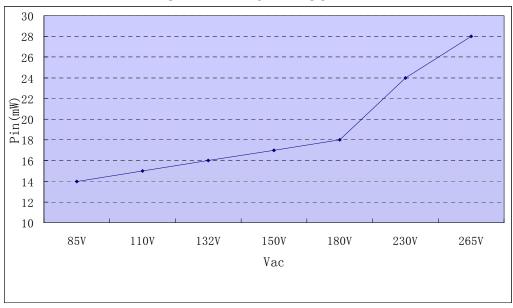
Parameter	Test condition	Min	Type	Max	units
input voltage		85		265	Vac
input frequency range		47		63	Hz
Average efficiency		75			%
Standby power	85-265Vac			30	mW
Output voltage			5		V
Output voltage ripple			80		mV
Output current			1		A
CV precision	0-1A			5	%
CC precision	2 - 5V			5	%
input UVP					
output OVP					
output OCP&SCP					

# 2 INPUT CHARACTERISTICS

#### **2.1 STANDBY POWER**

Vin(Vac)	Freq(Hz)	Pin(W)	Vo(Vrms)	lo(Arms)	Eff(%)	Pass/Fail
85	60	0.014	4.98	0		
110	60	0.015	4.97	0		
132	60	0.016	4.97	0		
150	60	0.017	4.96	0		
180	50	0.018	4.95	0		
230	50	0.024	4.98	0		
265	50	0.028	4.97	0		

#### STANDBY POWER CURVE

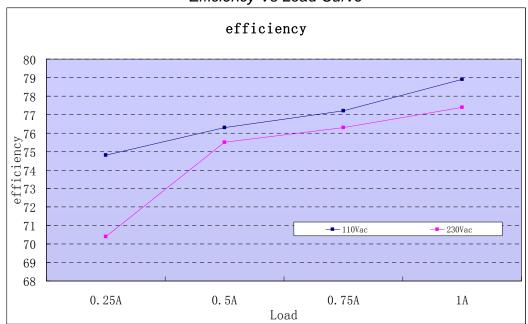


### 2.2 EFFICIENCY

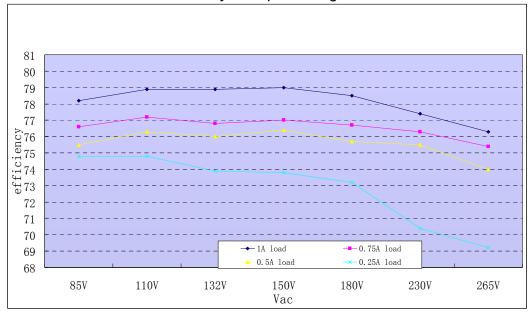
77.4% minimum with 230v input at 100% load.

Vin(Vac)	Freq(Hz)	Pin(W)	Vo(Vrms)	lo(Arms)	Eff(%)	Pass/Fail
85	60	6.32	4.94	1	78.2	
110	60	6.26	4.94	1	78.9	
132	60	6.27	4.94	1	78.9	
150	60	6.26	4.95	1	79	
180	50	6.30	4.94	1	78.5	
230	50	6.39	4.94	1	77.4	
265	50	6.47	4.94	1	76.3	

Efficiency Vs Load Curve



efficiency Vs Input Voltage curve



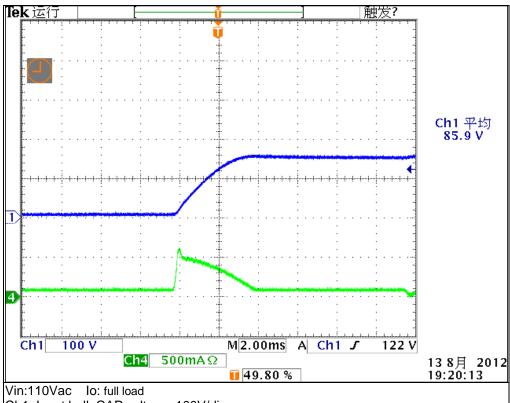
### 2.3 INPUT CURRENT

Vin(Vac)	Freq(Hz)	lin(Arms)	Pass/Fail
110	60	0.099	
230	50	0.066	

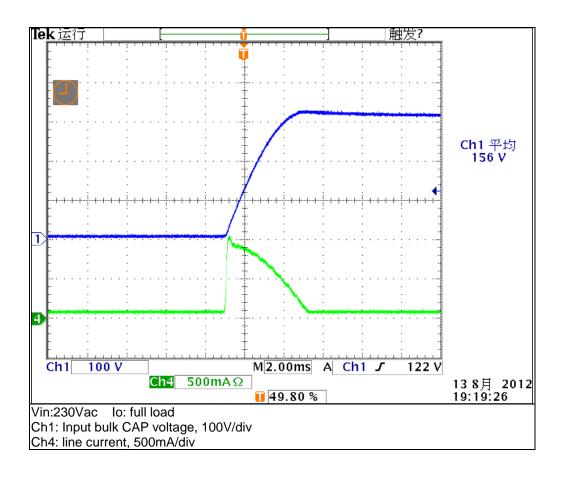
#### 2.4 INPUT INRUSH CURRENT

Pass/Fail criteria: XX Amps RMS maximum at low line and high line, full load.

Vin(Va	ac) Fred	q(Hz) lin(Arr	ns) Pass/Fail
110	6	<b>0.6</b>	
230	5	50 1	

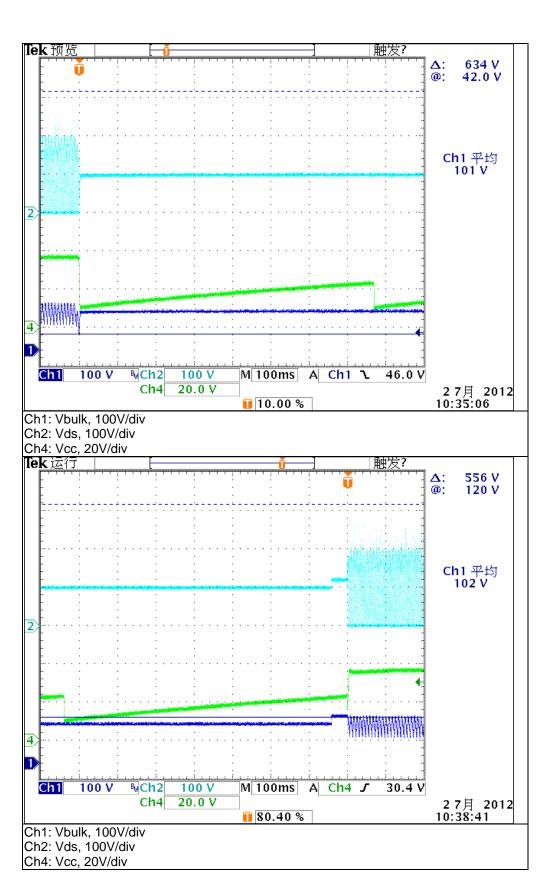


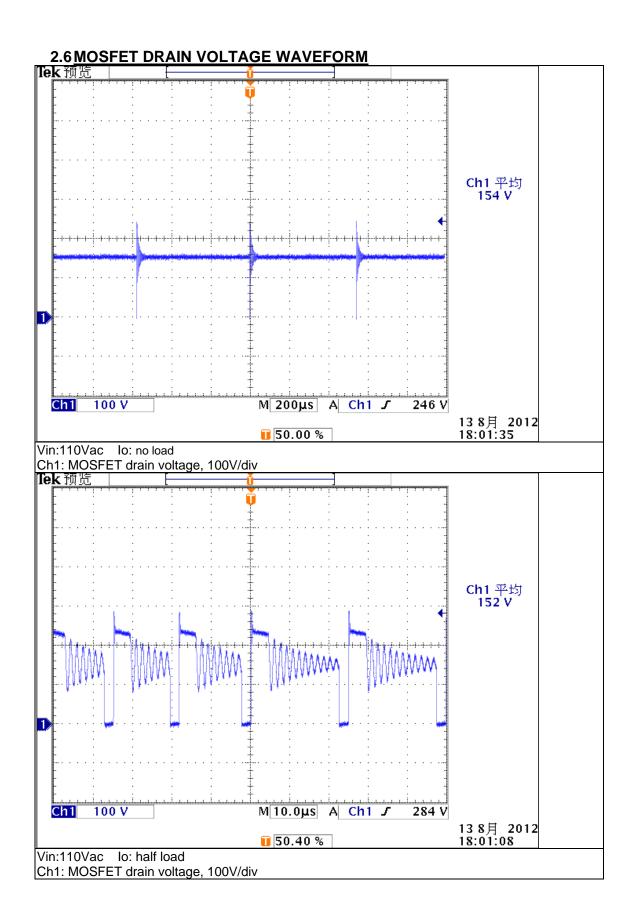
Ch1: Input bulk CAP voltage, 100V/div Ch4: line current, 500mA/div

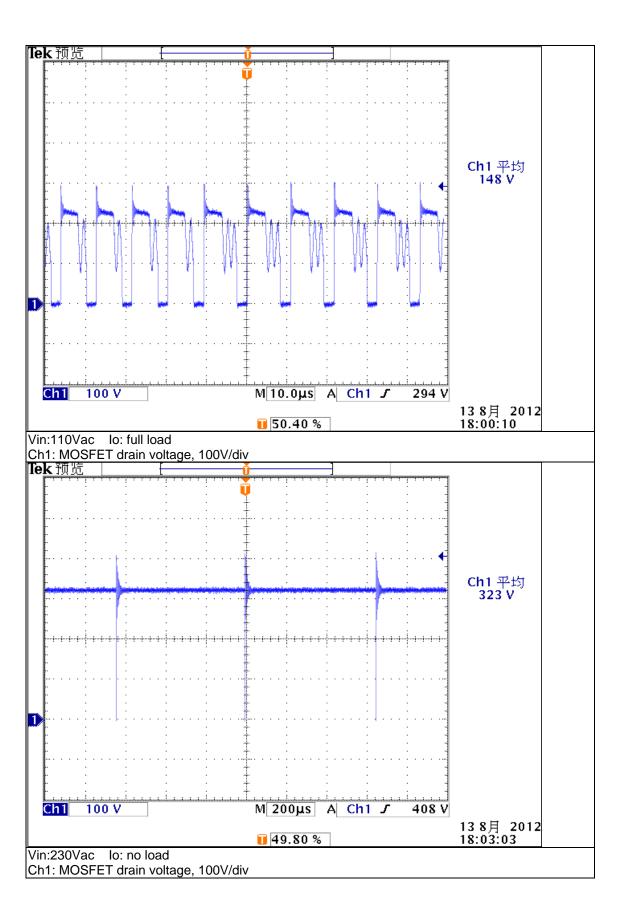


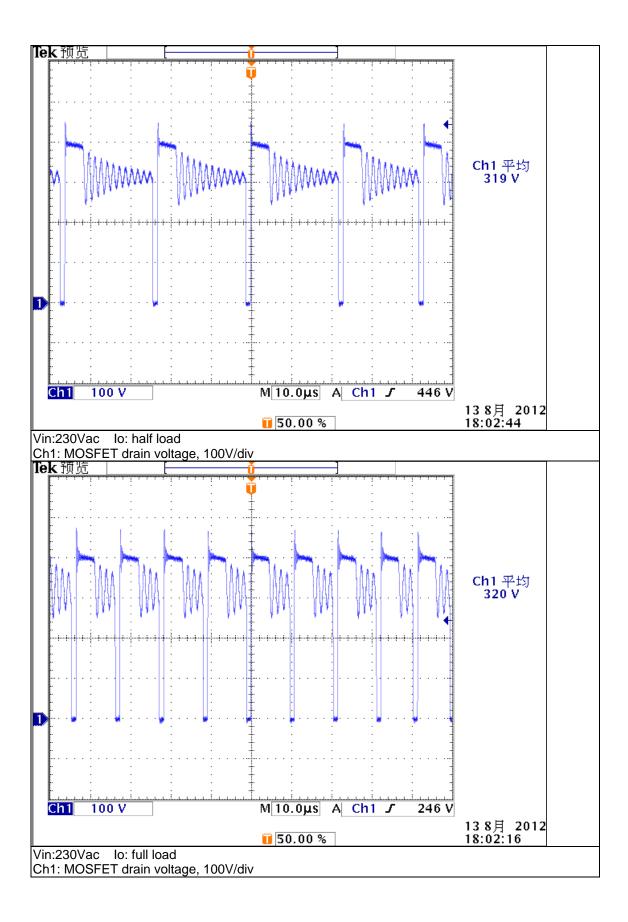
#### 2.5 INPUT UNDER-VOLTAGE PROTECTION

Switch-off at 42v Vbulk\_min(70Vac) Switch-on at 120v Vbulk\_max(85Vac)







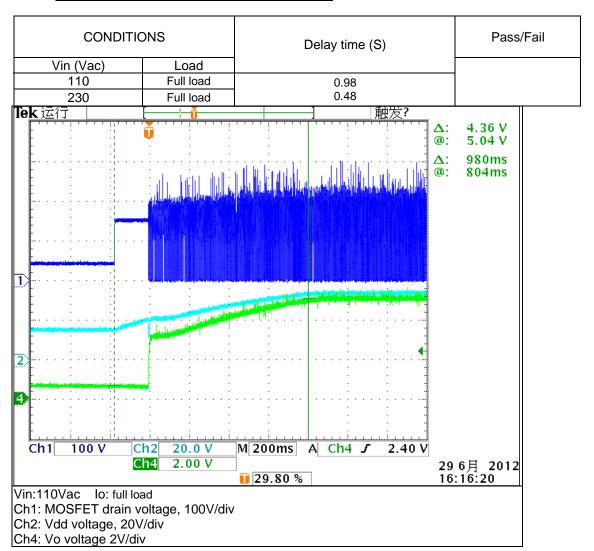


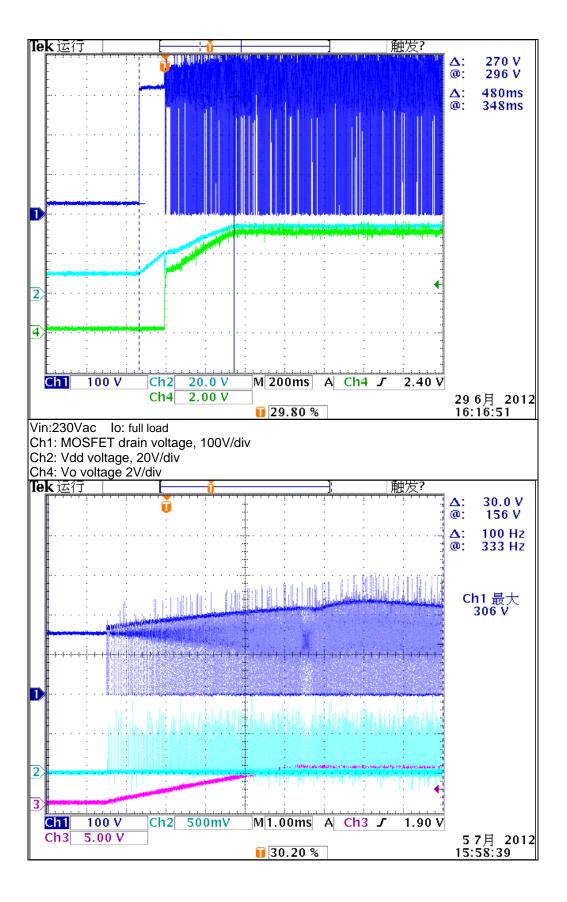
# 3. OUTPUT CHARACTERISTICS

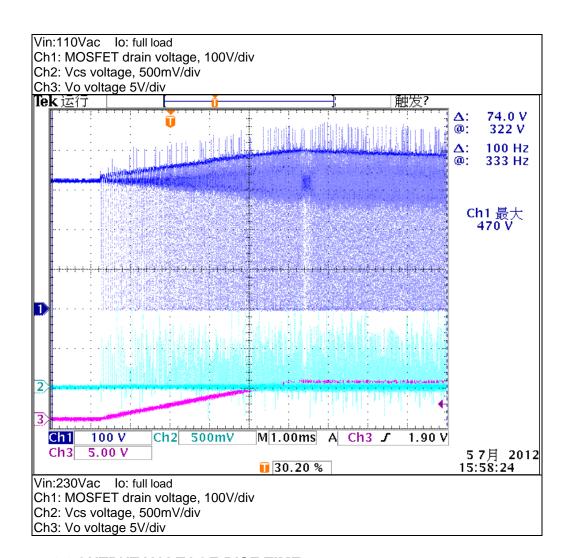
#### 2.7 OUTPUT VOLTAGE RANGE

ITEM	Vout (V)	lout(A)	Pass/Fail
Vin=110Vac	4.88	0.25	
	4.90	0.5	
	4.92	0.75	
	4.94	1	
	4.87	0.25	
Vin=230Vac	4.90	0.5	
	4.92	0.75	
	4.94	1	

### 2.8 TURN ON DELAY AND Vcs VOLTAGE

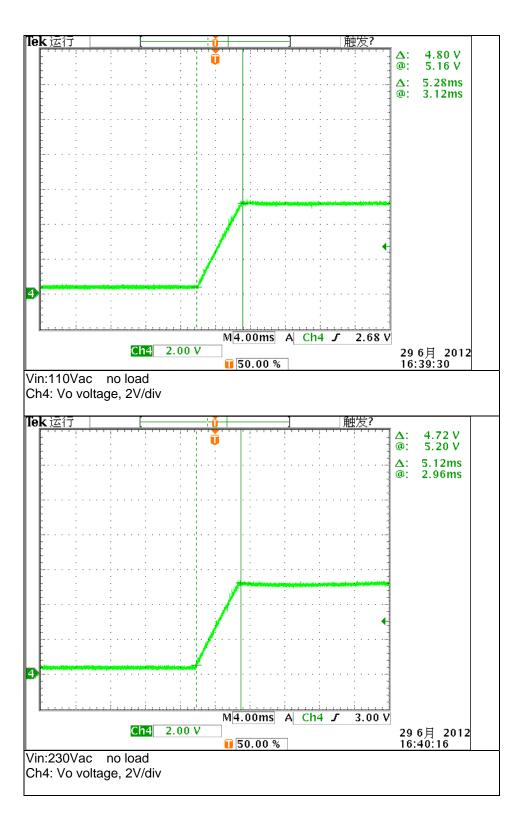




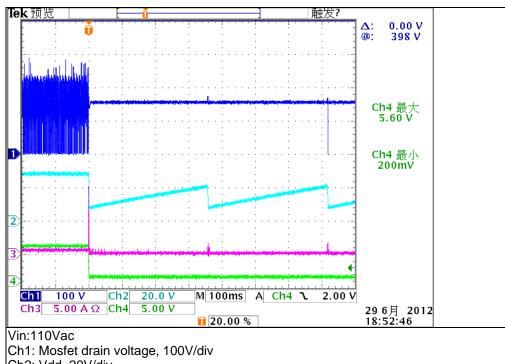


#### 2.9 OUTPUT VOLTAGE RISE TIME

CONDITIONS	Load condition	Va via a time a (ma)	Dagg/Fail
Vin (Vac)	Load Condition	Vo rise time(ms)	Pass/Fail
110	No load	5.28	
	Full load	800	
230	No load	5.12	
	Full load	360	

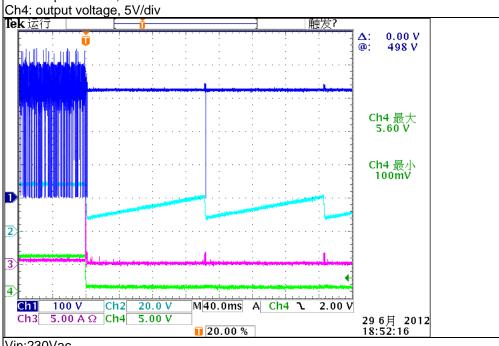


#### 2.10 **OUTPUT SHORT-CIRCUIT PROTECTION**



Ch2: Vdd, 20V/div

Ch3: output current, 5A/div



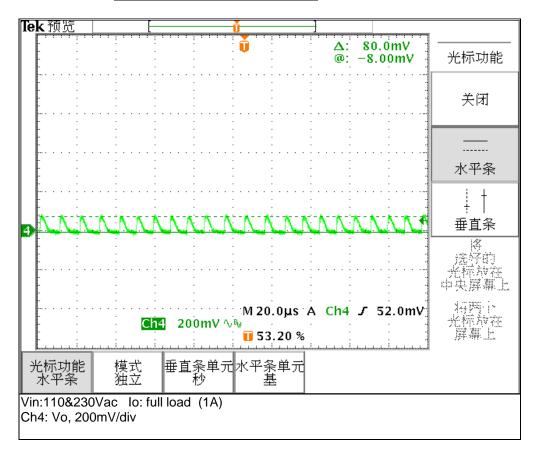
Vin:230Vac

Ch1: Mosfet drain voltage, 100V/div

Ch2: Vdd, 20V/div

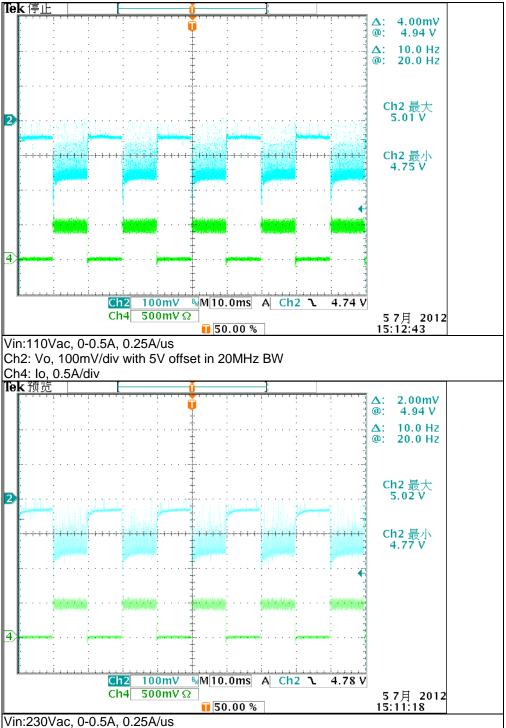
Ch3: output current, 5A/div Ch4: output voltage, 5V/div

#### 2.11 OUTPUT VOLTAGE RIPPLE



#### 2.12 <u>OUTPUT DYNAMIC REPONSE</u>

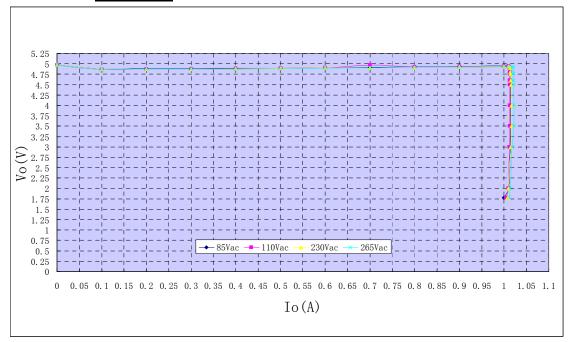
Test condition: 20cm cable with 70mohm resistance, a10uF E-CAP and a 0.1uF ceramic in parallel



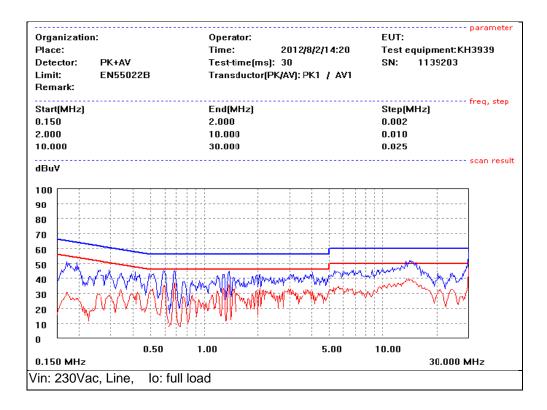
Ch2: Vo, 100mV/div with 5V offset in 20MHz BW

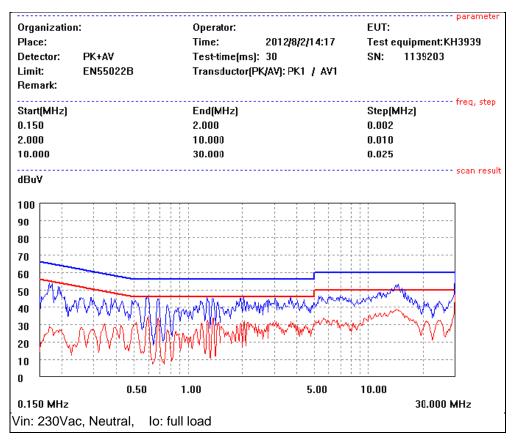
Ch4: lo, 0.5A/div

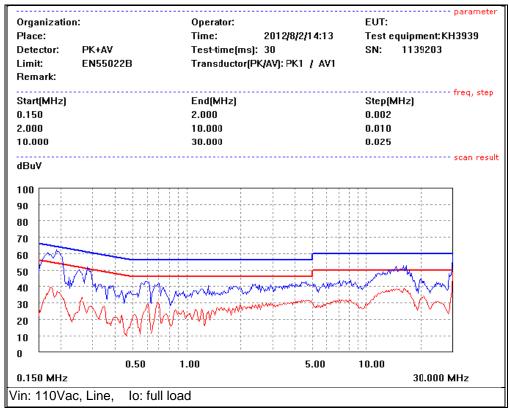
#### 2.13 <u>I/V CURVE</u>

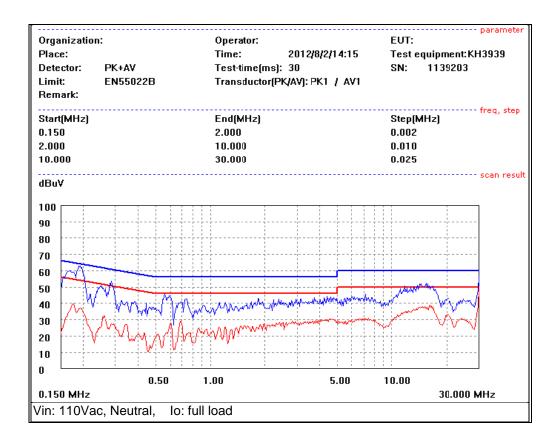


### 3 EMI Test









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